

Compact Modeling of Multiple-Gate MOSFETs

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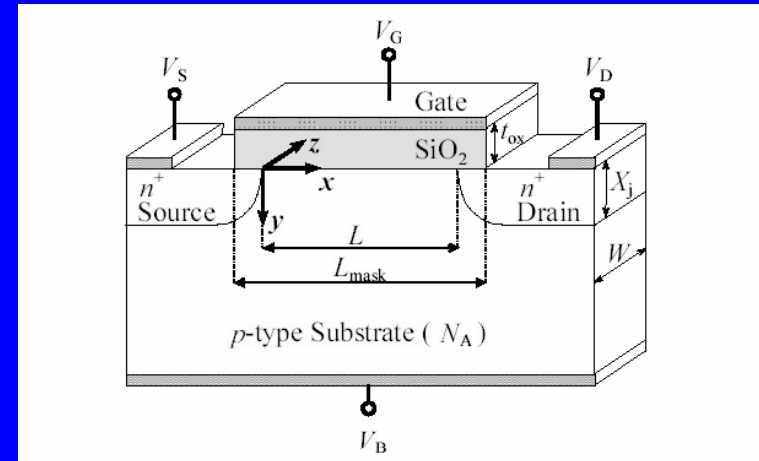
Outline

- **INTRODUCTION**
- **SYMMETRIC MG MOSFETS: PLANAR AND CYLINDRICAL**
- **A COMPLETE DOUBLE-GATE COMPACT MODEL WITH HARDWARE CALIBRATION**
- **GENERALIZATION OF CORE MODEL TO MULTIPLE-GATE MOSFETS**
- **OTHER APPROACHES**
- **CONCLUSION**

Impending Limit of Bulk MOSFETs

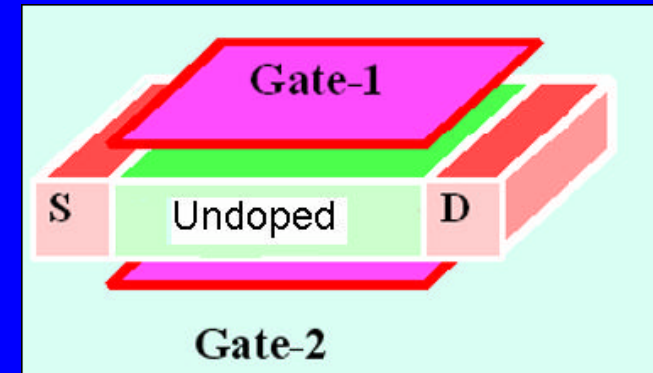
- Impending limit of bulk MOSFETs

- Gate oxide tunneling
- Threshold voltage limit
- Band-to-band tunneling
- Dopant fluctuation

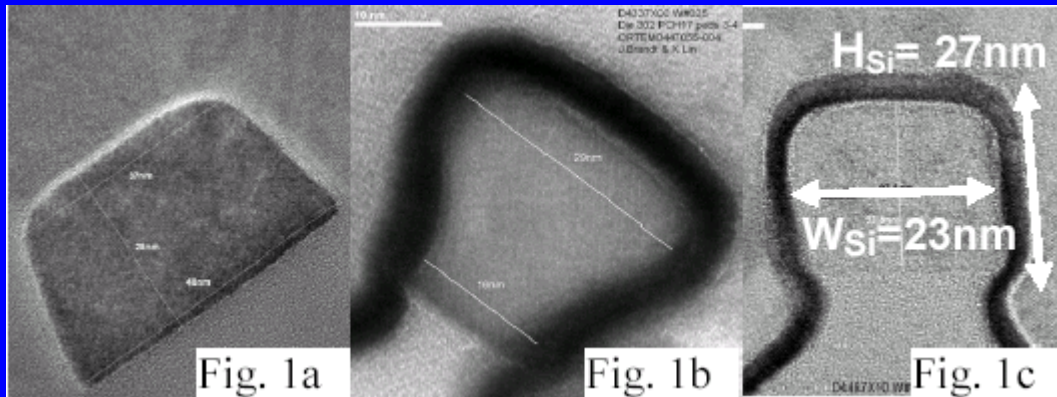


- Potential promise of double-gate MOSFETs

- Better control of SCEs
- Ideal subthreshold slope
- Better mobility without doping
- No dopant fluctuation



Fabrication Difficulty and Structural Variety

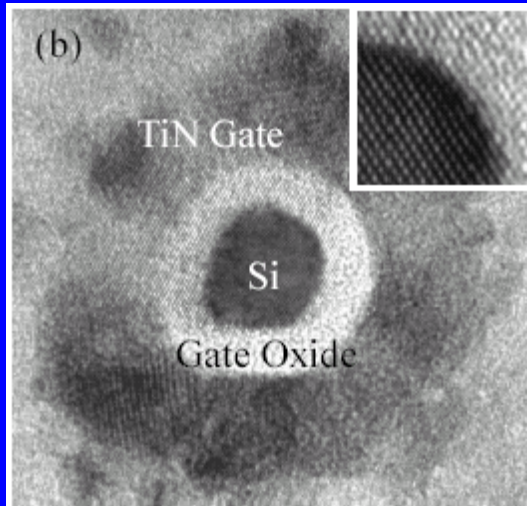


Tri-gate

J. Kavalieros et al,
VLSI Tech. Symp.,
2006)

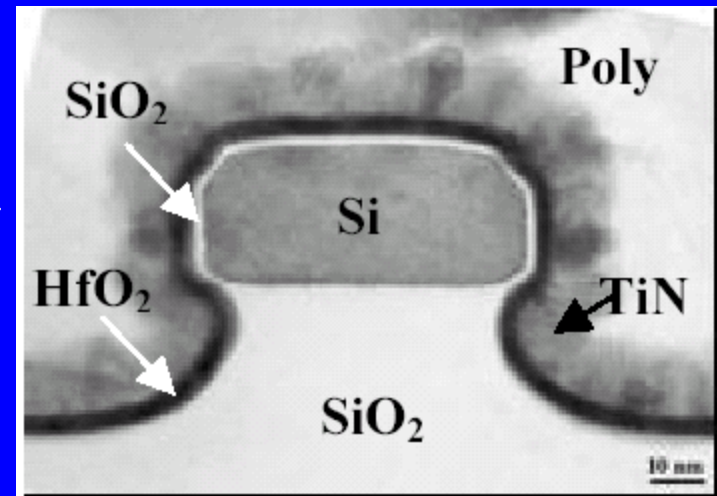
Nanowire

K. Cho et al,
IEDM, 2006

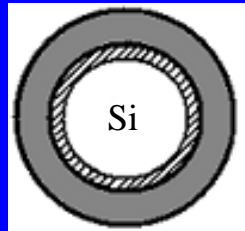


Ω -gate

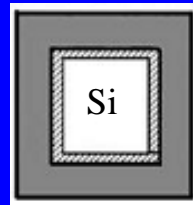
H. Lee et al,
VLSI Tech. Symp., 2006



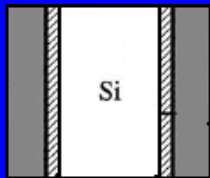
Unified Approach to Compact Modeling of Multiple-gate MOSFETs



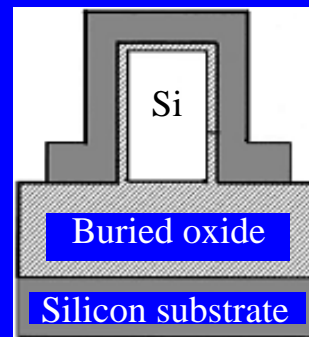
Surrounding-gate (SG)



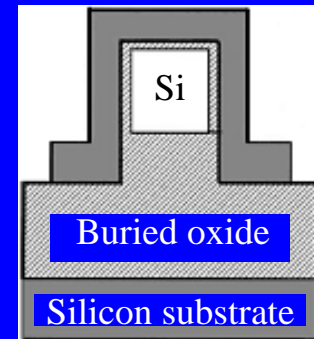
Quadruple-gate (QG)



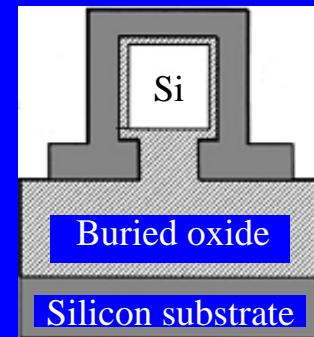
Double-gate (DG)



Triple-gate (TG)



Π -gate



Ω -gate

- DG and SG MOSFETs can be exactly solved
- QG model based on SG model
- TG approximated by the average of QG and DG
- Π -gate and Ω -gate models from TG model

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Compact Modeling

- **Bulk MOSFETs --- All based on the charge sheet model.**
 - Poisson's equation cannot be solved analytically due to presence of depletion and mobile charge.
 - Charge sheet approximation is necessary in all bulk compact models.
- **DG/SG MOSFETs --- Analytic potential function without charge-sheet approximation.**
 - Exact solution to Poisson's equation is possible due to the absence of depletion charge.
 - Volume inversion in subthreshold region requires a non-charge-sheet based model.

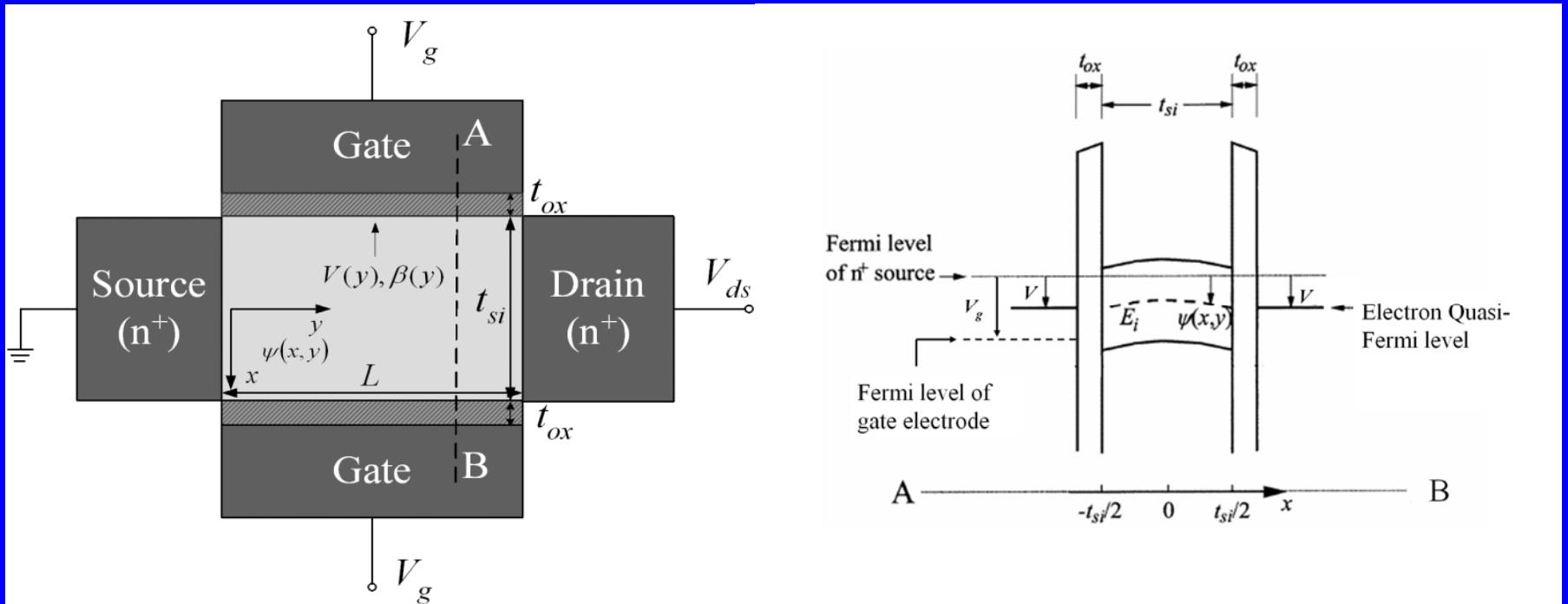
Analytic Solution for DG MOSFETs

- Poisson's equation under gradual channel approximation (GCA) with only mobile charge

$$\frac{d^2\psi}{dx^2} = \frac{q}{\epsilon_{si}} n_i e^{q(\psi-V)/kT}$$

V : quasi-Fermi potential

- Current continuity equation: $I_{ds} = \mu W Q_i dV / dy = const.$



Drain Current for Planar DG MOSFETs

- Drain current model

$$I_{ds} = \mu \frac{W}{L} \frac{8\epsilon_{si}}{t_{si}} \left(\frac{kT}{q} \right)^2 \left[-2\beta \tan \beta + \beta^2 - 2r\beta^2 \tan^2 \beta \right] \Big|_{\beta_s}^{\beta_d}$$

$$r = \epsilon_{si} t_{ox} / \epsilon_{ox} t_{si}$$

β_s and β_d are given by the boundary condition

$$\frac{q(V_g - \Delta\phi - V)}{2kT} - \ln \left[\frac{2L_{Di}}{t_{si}} \right] = \ln \beta - \ln [\cos \beta] + 2r\beta \tan \beta$$

for $V=V_s, V_d$

$$L_{Di} = \sqrt{2\epsilon_{si} kT / q^2 n_i}$$

- Continuous for all regions of MOSFET operation
- Implicit equations for β_s and β_d

Taur et al., EDL 2004

Continuous Model

• All regions of MOSFET operation are covered under one continuous function

□ Linear region: $\beta_s, \beta_d \sim \pi/2$

$$I_{ds} = 2\mu C_{ox} \frac{W}{L} (V_g - V_t - V_{ds}/2)V_{ds}$$

□ Saturation: $\beta_s \sim \pi/2, \beta_d \ll 1$

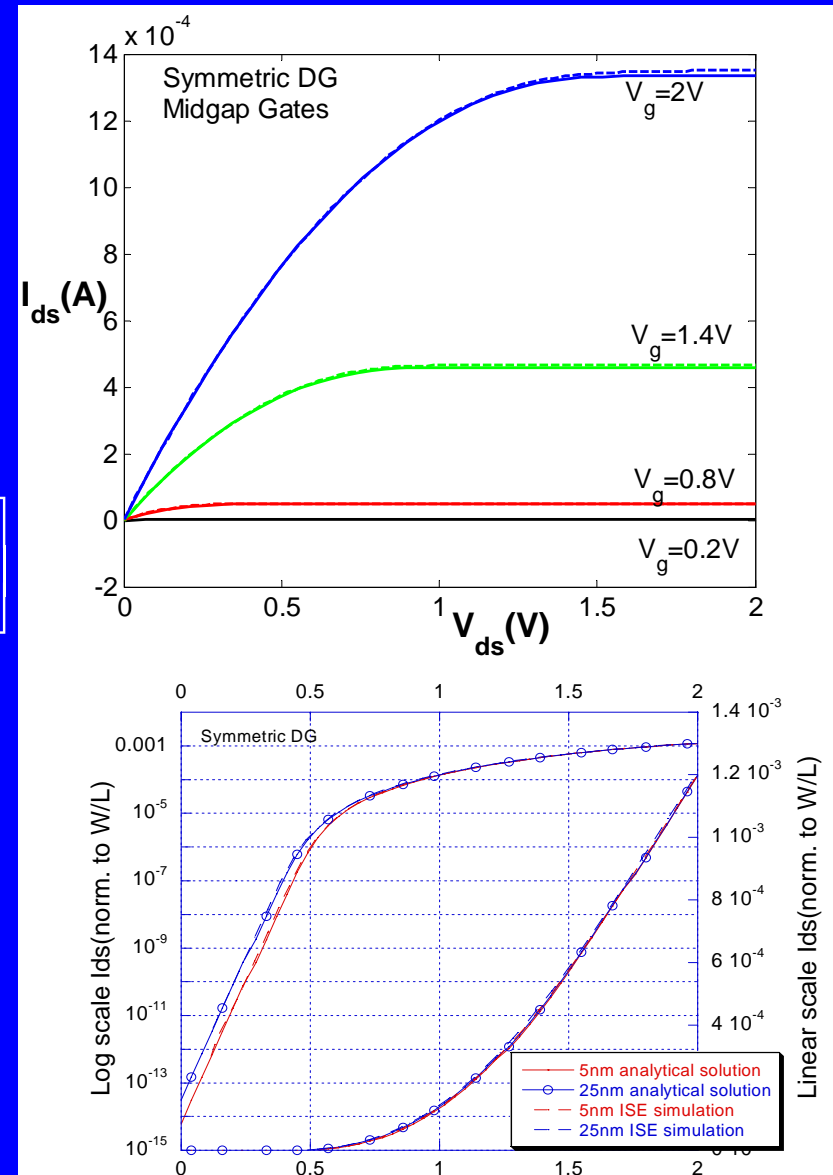
$$I_{ds} = \mu C_{ox} \frac{W}{L} \left[(V_g - V_t)^2 - \frac{8rk^2T^2}{q^2} e^{q(V_g - V_t - V_{ds})/kT} \right]$$

□ Subthreshold: $\beta_s, \beta_d \ll 1$

$$I_{ds} = \mu \frac{W}{L} kT n_i t_{si} e^{q(V_g - \Delta\phi)/kT} (1 - e^{-qV_{ds}/kT})$$

Saturation and “volume inversion” in subth. come naturally from the analytic, non-charge-sheet model.

Comparison with 2-D Numerical simulation



Analytic Solution for SG MOSFETs

- Poisson's equation under GCA

$$\frac{d^2\psi}{d\rho^2} + \frac{1}{\rho} \frac{d\psi}{d\rho} = \frac{q}{\epsilon_{si}} n_i e^{q(\psi-V)/kT}$$

- Drain current model

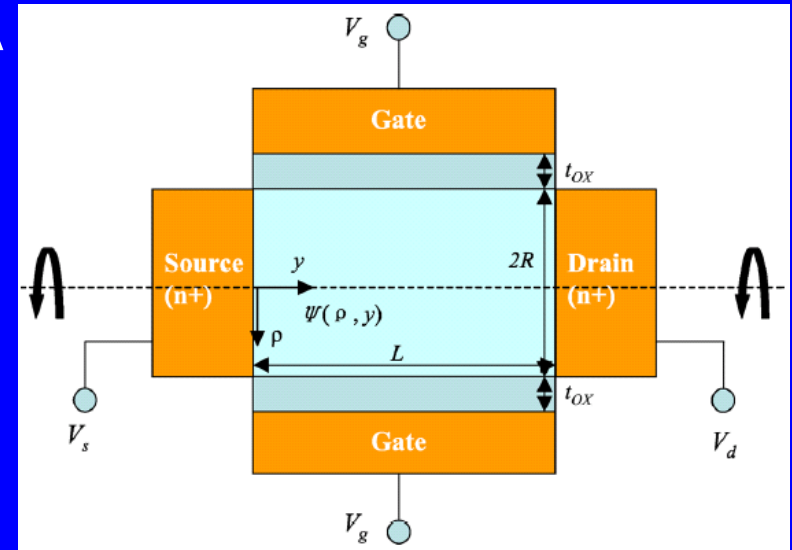
$$s = 2\epsilon_{si} \ln(1 + t_{ox}/R) / \epsilon_{ox}$$

$$I_{ds} = \mu \frac{8\pi\epsilon_{si}}{L} \left(\frac{2kT}{q} \right)^2 \left[(-2/\alpha - \ln \alpha) + s(-1/\alpha^2 + 2/\alpha) \right] \Big|_{\alpha_s}^{\alpha_d}$$

α_s and α_d are given by the boundary condition

$$\frac{q(V_g - \Delta\phi - V)}{2kT} - \ln \left(\frac{2L_{Di}}{R} \right) = \ln \sqrt{1 - \alpha} - \ln \alpha + s \frac{1 - \alpha}{\alpha}$$

for $V=V_s, V_d$



Explicit Solutions for DG and SG MOSFETs --- General Method

Solve $f(x; a, b, c) = 0$; x is an implicit function of a, b, c ; employ a general method similar to PSP's explicit solution of surface potential in the charge-sheet model.

1. Guess a continuous starting function $x_1 = g(a, b, c)$

- Has the appropriate asymptotic behaviors

2. Modify the starting function with correction term

$$x_2 = g(a, b, c) + h(a, b, c)$$

$$h = -\frac{f_{g0}}{f_{g1}} \left(1 + \frac{f_{g0}f_{g2}}{2f_{g1}^2} + \frac{f_{g0}^2(3f_{g2}^2 - f_{g1}f_{g3})}{6f_{g1}^4} \right)$$

$$f_{gn} = \left. \frac{\partial^n f(x; a, b, c)}{\partial x^n} \right|_{x=g(a, b, c)}$$

3. Another correction may be needed to further improve accuracy

$$x_3 = g(a, b, c) + h(a, b, c) + w(a, b, c)$$

Explicit Solutions for DG and SG MOSFETs --- Accuracy

- Simplified equation for SG

$$g(z; s, G) = \ln(\sqrt{z + z^2}) + sz - G = 0$$

$$1. \quad z_1 = \sqrt{\left(\frac{1}{2s^2}\right)^2 + \left(\frac{1}{s}\right)^2 \ln^2(1 + e^G)} - \frac{1}{2s^2}$$

2.

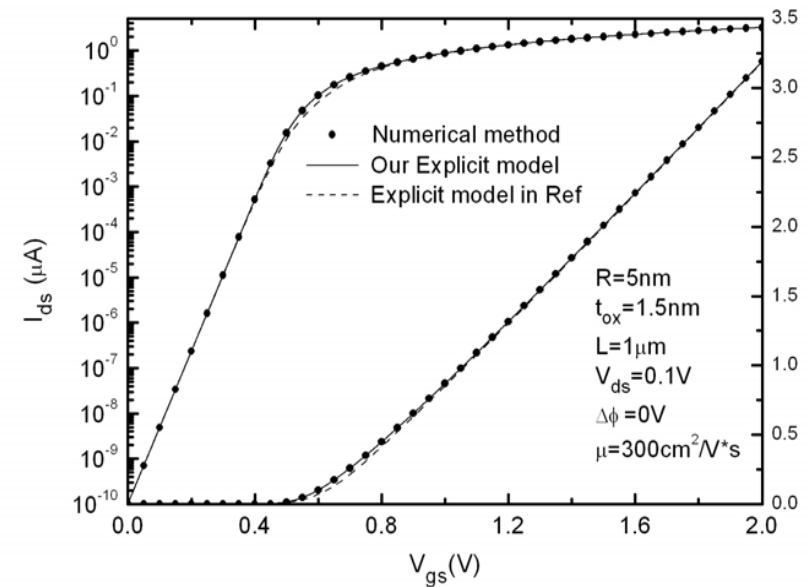
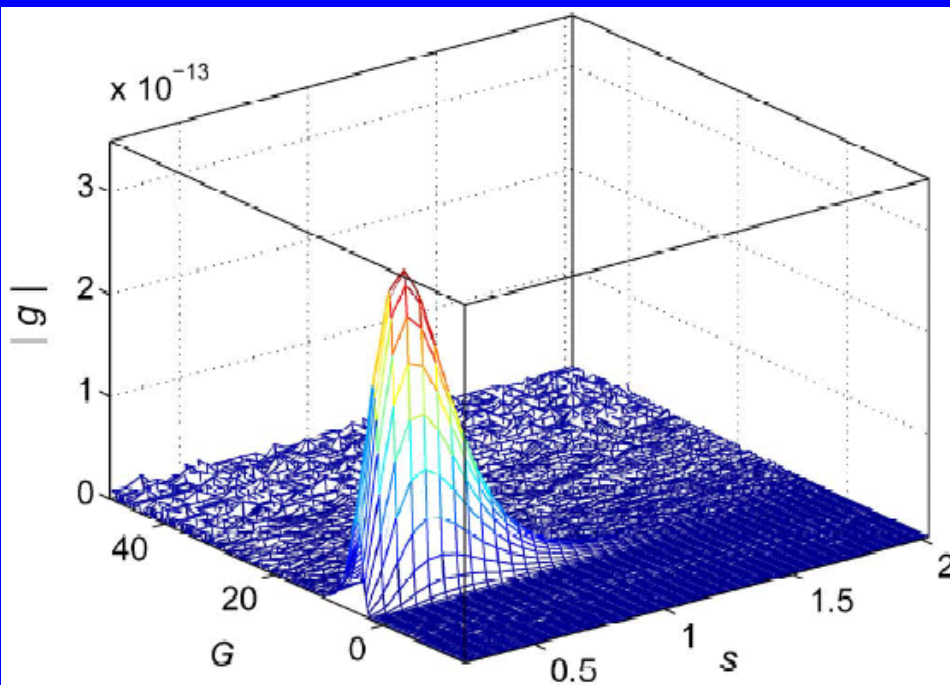
$$\eta_0 = \frac{1}{2} \ln(z_1 + z_1^2) + sz_1 - G$$

$$\eta_1 = \frac{1}{2z_1} + \frac{1}{2(1+z_1)} + s$$

$$\eta_2 = -\frac{1}{2z_1^2} - \frac{1}{2(1+z_1)^2}$$

$$\eta_3 = \frac{1}{z_1^3} + \frac{1}{(1+z_1)^3}$$

$$z_2 = z_1 - \frac{\eta_0}{\eta_1} \left(1 + \frac{\eta_0 \eta_2}{2\eta_1^2} + \frac{\eta_0^2 (3\eta_2^2 - \eta_1 \eta_3)}{6\eta_1^4} \right)$$



Charge and Capacitance Model

- Ward-Dutton partition method

$$Q_g = -W \int_0^L Q_i(y) dy \quad Q_d = W \int_0^L \frac{y}{L} Q_i(y) dy \quad Q_s = W \int_0^L \left(1 - \frac{y}{L}\right) Q_i(y) dy$$

- Definitions of transcapacitances

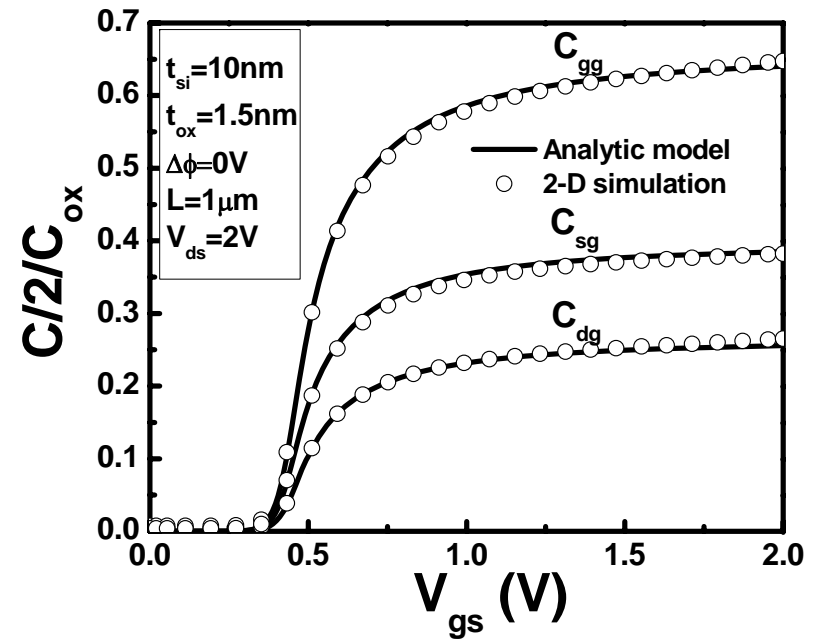
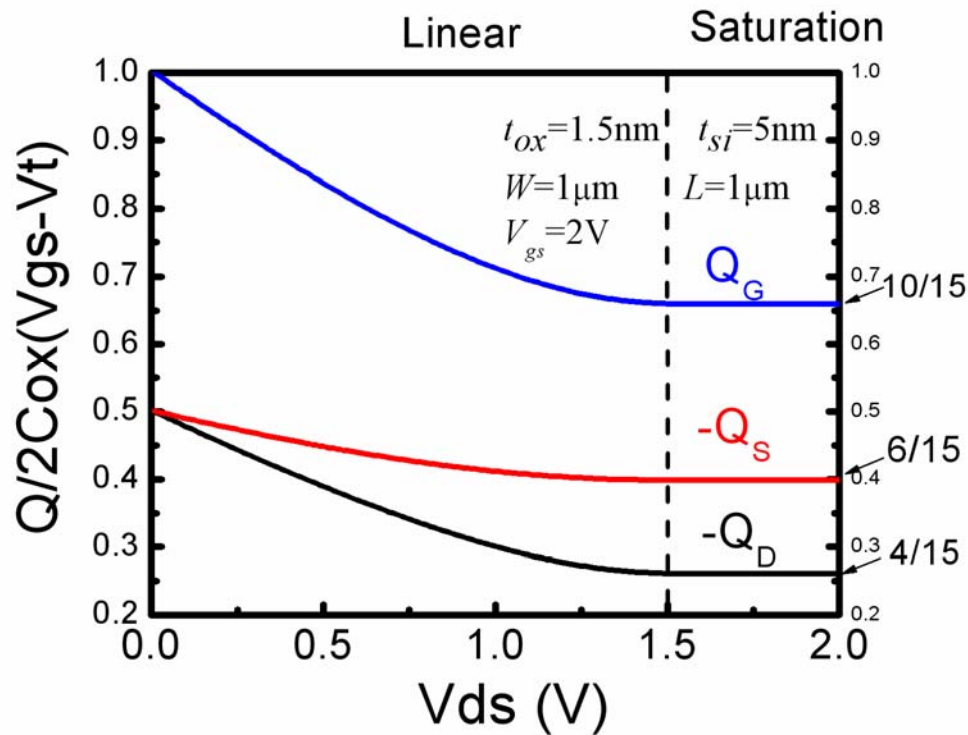
$$C_{kk} = \frac{\partial Q_k}{\partial V_k} \quad C_{kl} = -\frac{\partial Q_k}{\partial V_l} \quad l \neq k$$

- Capacitances can be derived as a function of Q, g and I

$$C_{dd} = -\frac{L^2 g_{ds}^2}{\mu I_{ds}} - \frac{2Q_D}{I_{ds}} g_{ds} \quad C_{dg} = -\frac{L^2 g_{ds}^2}{\mu I_{ds}} + \frac{Q_G}{I_{ds}} (g_m + g_{ds}) + \frac{2Q_D}{I_{ds}} g_m$$

$$C_{gd} = -\frac{L^2 g_{ds}^2}{\mu I_{ds}} + \frac{Q_G}{I_{ds}} g_{ds} \quad C_{gg} = -\frac{L^2 \left[(g_m + g_{ds})^2 - g_{ds}^2 \right]}{\mu I_{ds}} + \frac{Q_G}{I_{ds}} g_m$$

Charge/Capacitance Model Validation



Outline

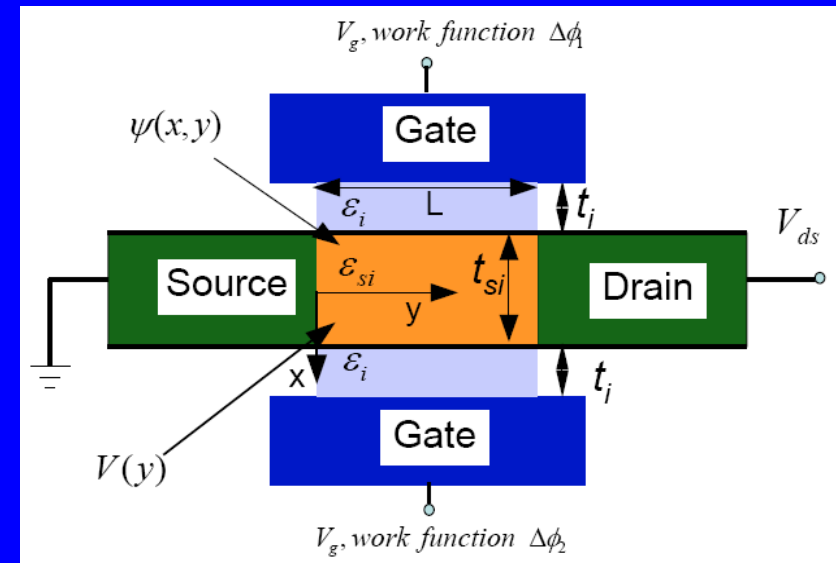
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Short Channel Effect

- 2D Poisson's Eq. in subthreshold:

$$\frac{\partial}{\partial x} \left(\epsilon \frac{\partial \psi}{\partial x} \right) + \frac{\partial}{\partial y} \left(\epsilon \frac{\partial \psi}{\partial y} \right) = 0$$

- Solve 2-D boundary value problem analytically:



Top gate : $\psi(-t_{si}/2 - t_i, y) = V_g - \Delta\phi_1$ $0 < y < L$

Bottom gate: $\psi(t_{si}/2 + t_i, y) = V_g - \Delta\phi_2$ $0 < y < L$

Source : $\psi(x, 0) = E_g / 2q$ $-t_{si}/2 < x < t_{si}/2$

Drain : $\psi(x, L) = V_{ds} + E_g / 2q$ $-t_{si}/2 < x < t_{si}/2$

Short Channel Effect

- 2-D potential function in the subthreshold region

$$\psi(x, y) = \frac{\Delta\phi_1 - \Delta\phi_2}{t_{si} + 2t_i\epsilon_{si}/\epsilon_{ox}} x + V_g - \frac{\Delta\phi_1 + \Delta\phi_2}{2} + \frac{b_1 \sinh[\pi(L-y)/\lambda_1] + c_1 \sinh(\pi y/\lambda_1)}{\sinh(\pi y/\lambda_1)} \cos(\pi x/\lambda_1)$$

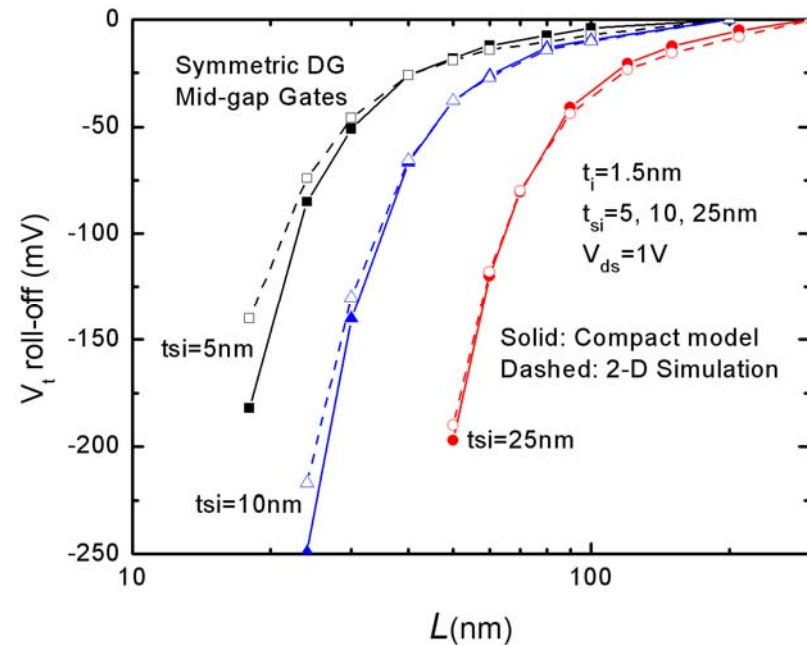
$$b_1, c_1 = B \left(E_g / 2q + V_{s,d} + \frac{\Delta\phi_1 + \Delta\phi_2}{2} - V_{g0} \right)$$

- **Scale length**

$$\tan\left(\frac{\pi t_{ox}}{\lambda_1}\right) \tan\left(\frac{\pi t_{si}}{2\lambda_1}\right) = \frac{\epsilon_{ox}}{\epsilon_{si}}$$

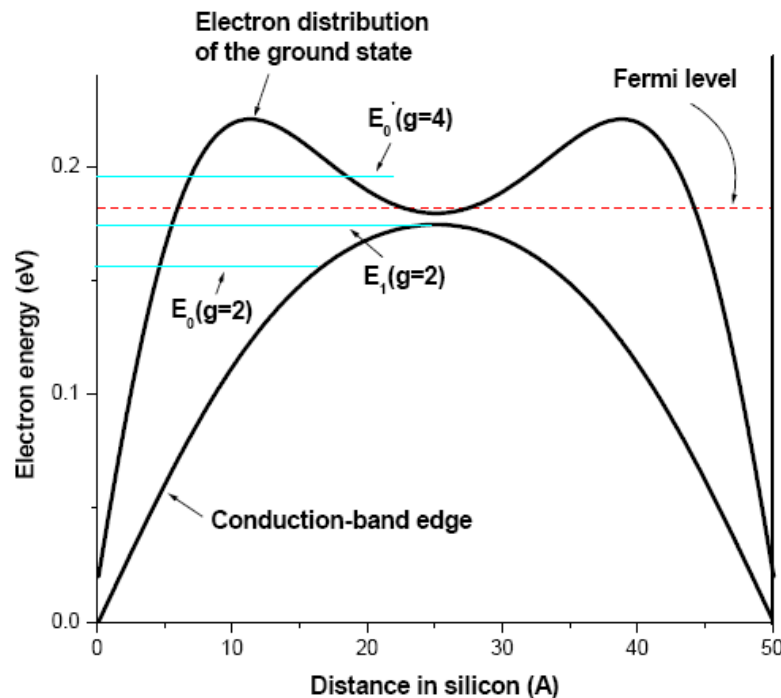
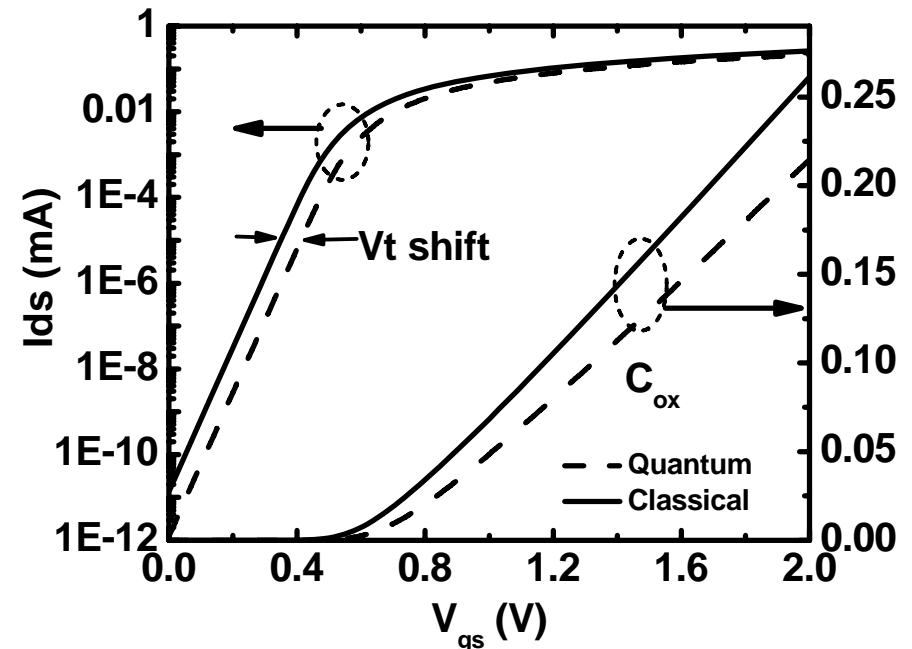
- **Subthreshold current**

$$I_{ds} = \frac{\mu W (kT/q) [1 - \exp(-qV_{ds}/kT)]}{\int_0^L \frac{dy}{\int_{-t_{si}/2}^{t_{si}/2} n_i e^{q\psi(x,y)/kT} dx}}$$



Quantum Effect: Poisson + Schrodinger eqs.

➤ Slope: QM effect degrades the inversion capacitance because of deeper charge centroid.



➤ Vt shift: QM effect causes higher Vt due to higher ground state energy.

Quantum Effect

- Compact model for V_t shift

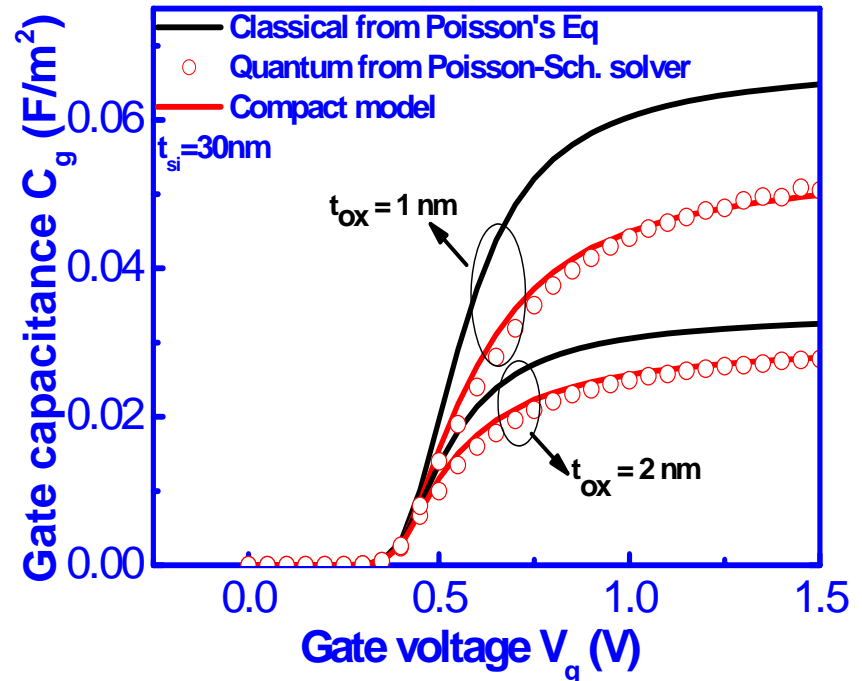
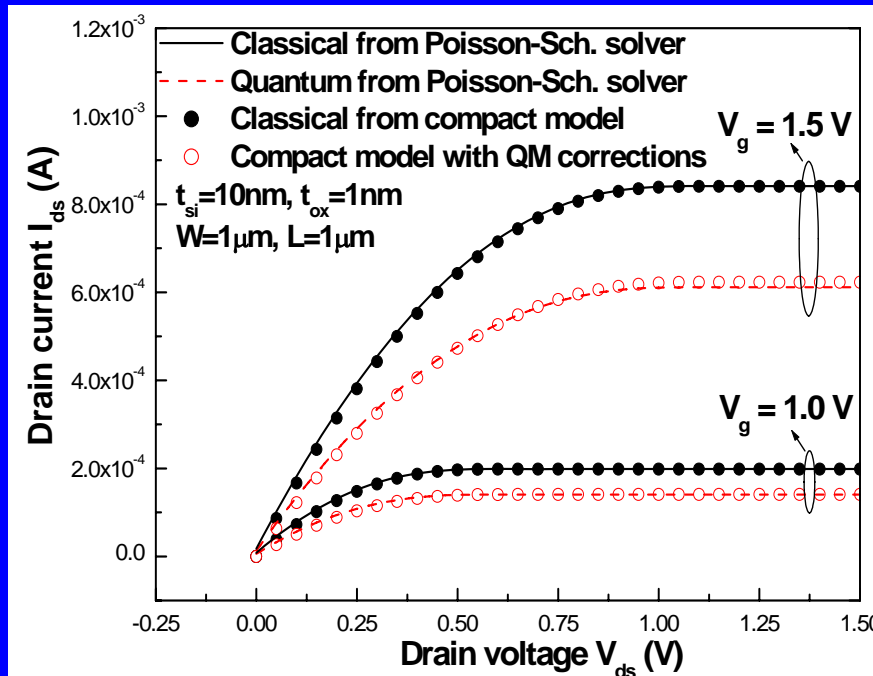
$$\Delta V_t = \frac{E_1}{q} = \frac{\hbar^2 \pi^2}{2q m^* t_{si}^2}$$

- Compact model for gate capacitance degradation

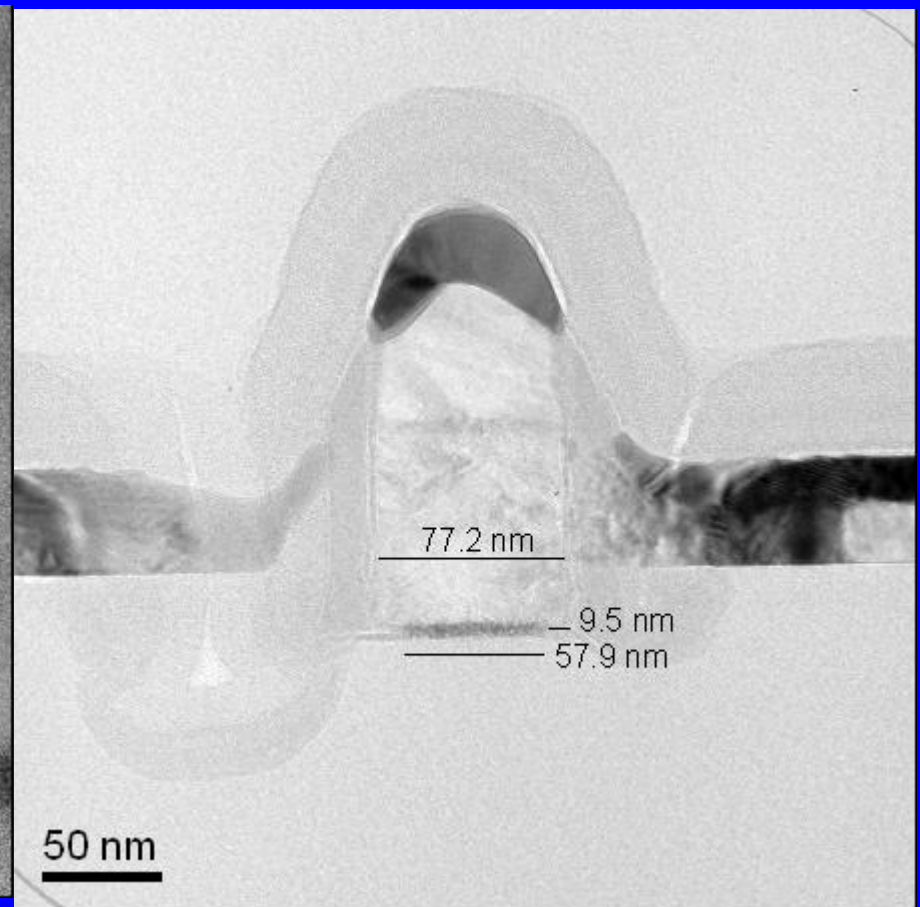
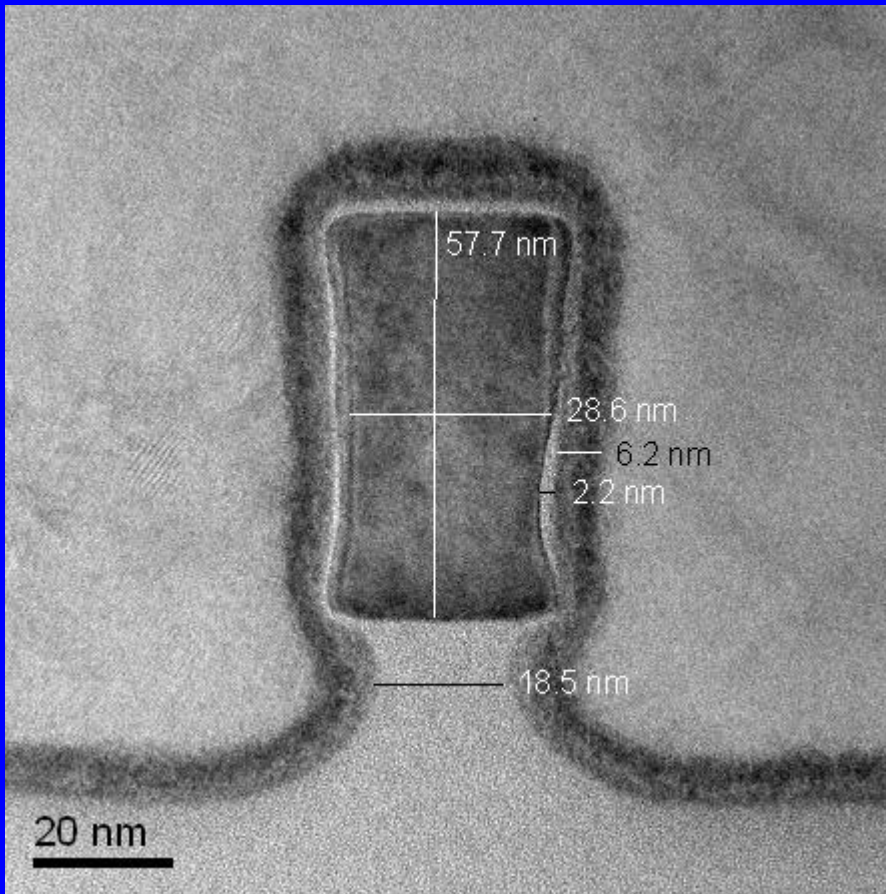
Effective oxide thickness

$$t_{oxeff} = t_{ox} + \frac{\epsilon_{si}}{\epsilon_{ox}} \delta t_{inv}$$

$$\delta t_{inv} = \left(\frac{21 \epsilon_{si} \hbar^2}{2 m^* q Q_i} \right)^{1/3}$$



FinFET Hardware Calibration

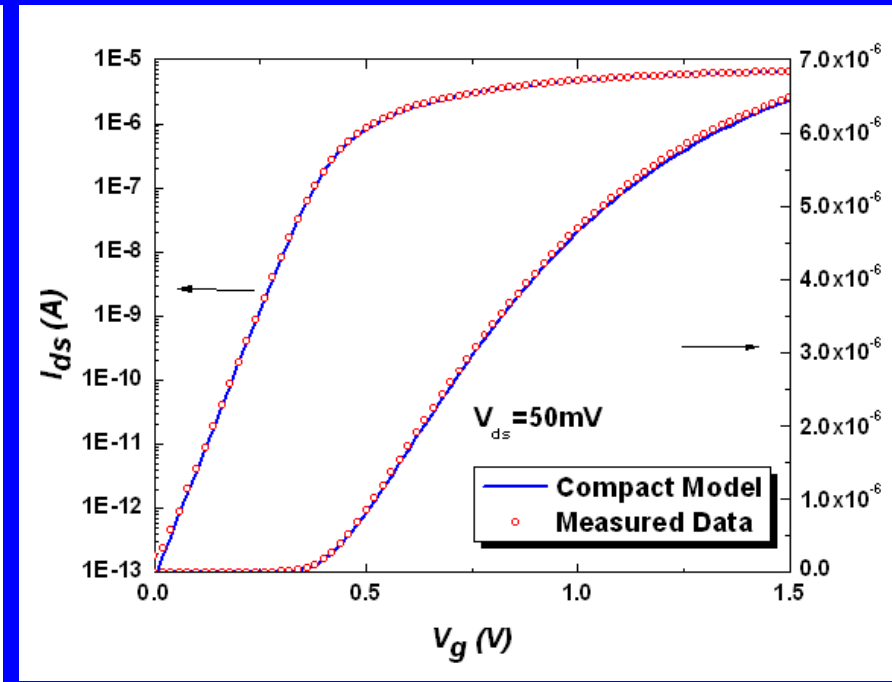
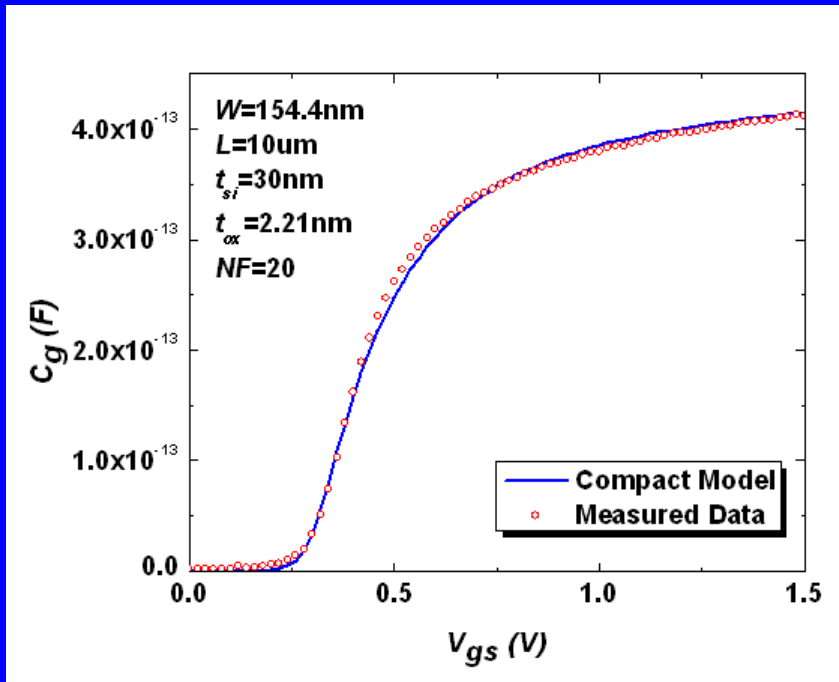


Acknowledgement: Wade Xiong, Texas Instruments.

Hardware Calibration Procedure

- Start with C-V Data:
 - Calibrate Oxide Thickness, Effective Device Width, with Quantum Mechanical Effects.
- Long Channel Devices:
 - Calibrate Mobility from low drain-bias $I_{ds}-V_g$ data.
- Short Channel Devices:
 - Low Drain $I_{ds}-V_g$ --- Calibrate Source-Drain series resistance.
 - SCE: V_t rolloff, DIBL, subthreshold slope --- Determine effective channel length consistent with data.
 - High Drain $I_{ds}-V_g$ and $I_{ds}-V_d$ --- Calibrate saturation velocity, channel length modulation.

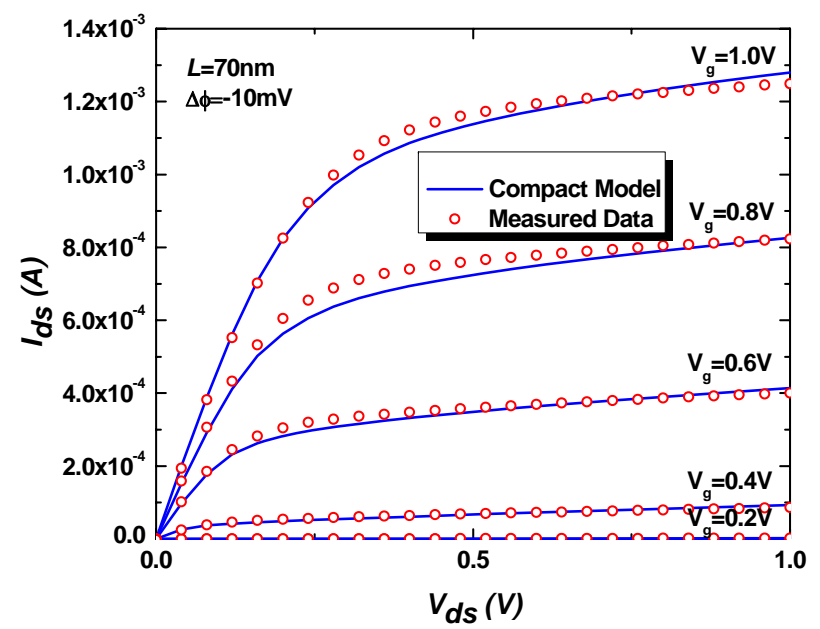
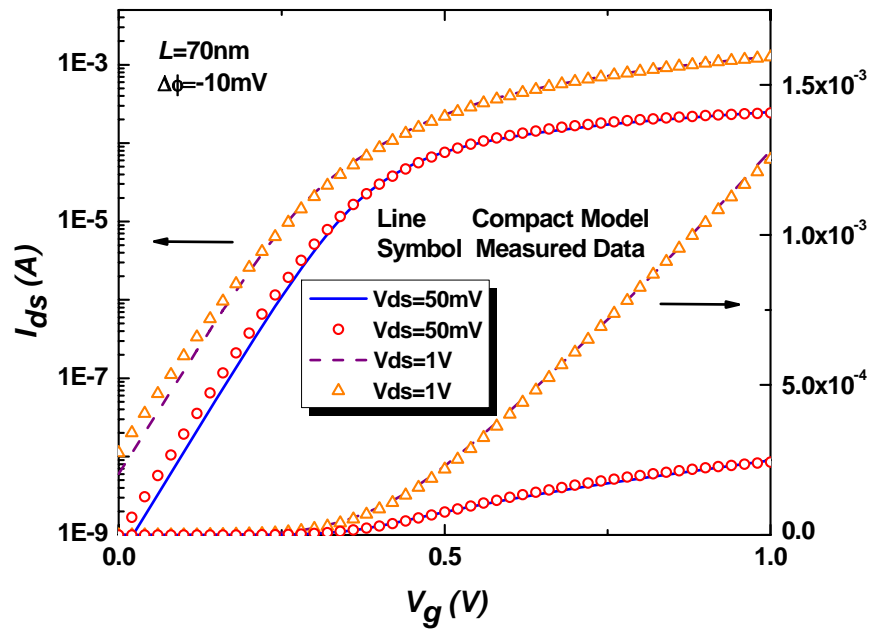
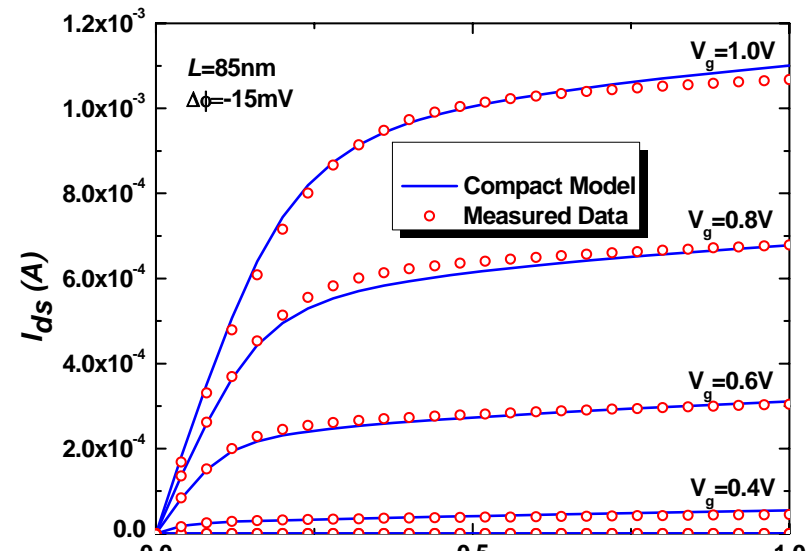
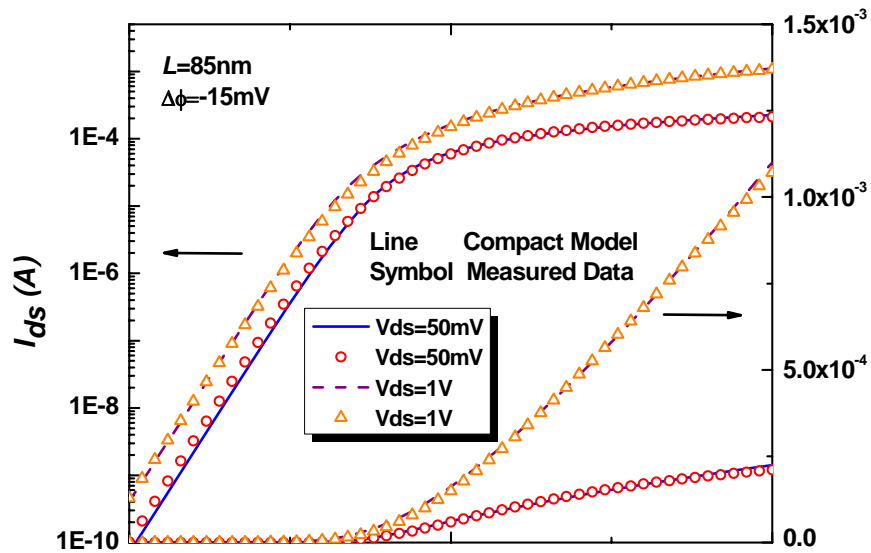
FinFET hardware calibration



- Quantum-mechanical models are necessary to obtain agreement with experimental C-V data.
- Mobility model consists of impurity scattering and phonon scattering terms.

$$\mu = \frac{\mu_1 \mu_2}{\mu_1 + \mu_2} \quad \text{where} \quad \mu_1 = \frac{740}{1 + \left(\frac{E_{eff}}{0.52e6} \right)^{1.25}} \quad \mu_2 = 540 \left(1 + \left(\frac{E_{eff}}{0.075e6} \right)^{1.55} \right)$$

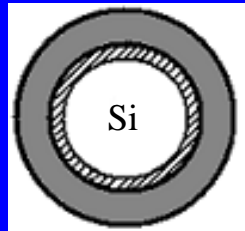
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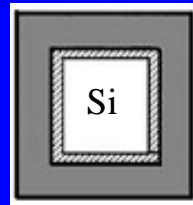
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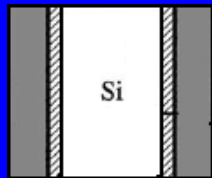
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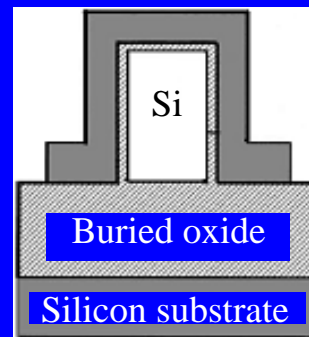
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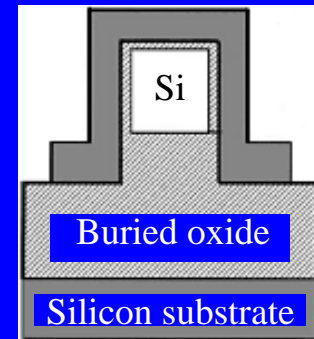
Quadruple-gate (QG)



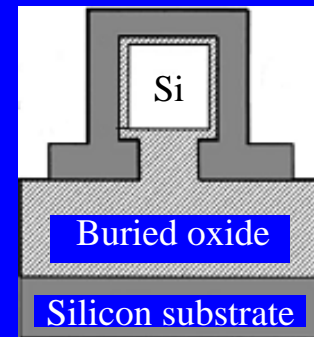
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Triple-gate (TG)



Π -gate

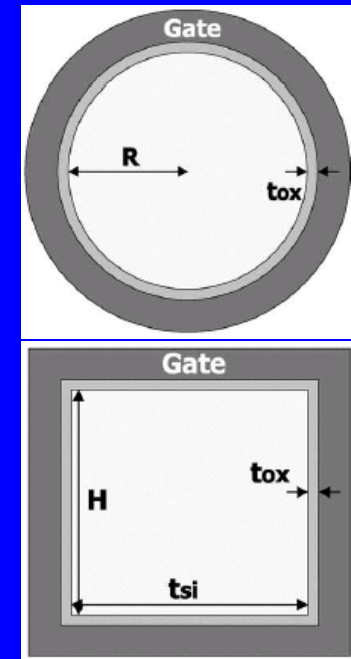


Ω -gate

- DG and SG MOSFETs can be exactly solved.
- QG model based on modified SG model.
- TG represented by the average of QG and DG.
- Π -gate and Ω -gate models extended from TG model.

From SG to QG

- Asymptotic behaviors:
 - Volume inversion: In subthreshold, Q_m is proportional to the cross section area of silicon body.
 - Surface inversion layer: Far above threshold, Q_m is proportional to the perimeter of silicon body. (no visible corner effect)



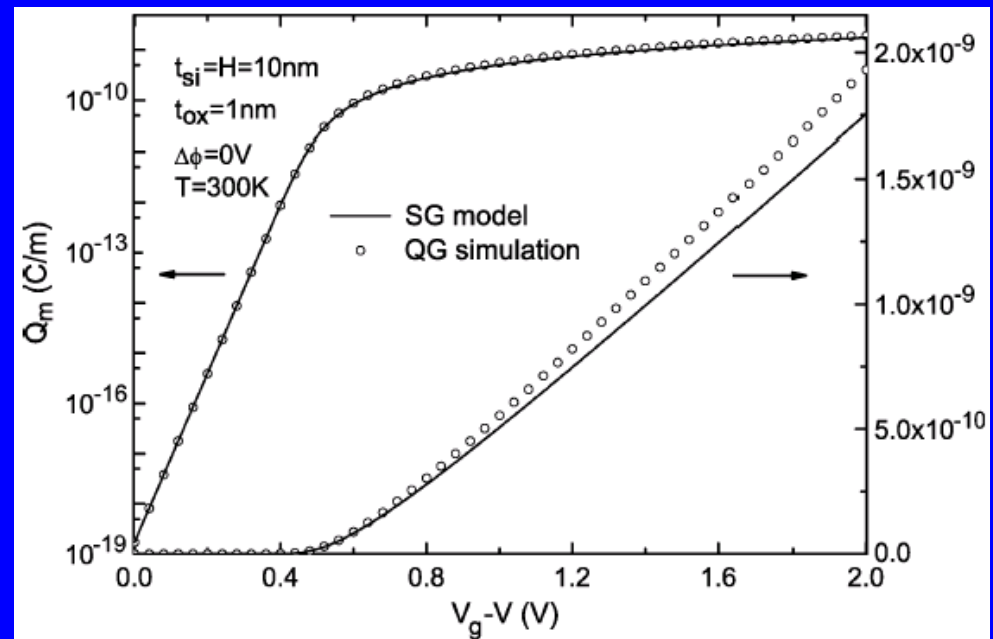
- Compare Q_m - V_g Curves of QG and SG:

- QG parameters: t_{si} , H , and t_{ox} .

- SG parameters:

$R = \sqrt{t_{si} H / \pi}$ and t_{ox} .

Same cross section area as QG



From SG to QG

- $Q_m(QG)/Q_m(SG)$ vs α :

➤ Almost linear behavior

$$Q_m(QG)/Q_m(SG) \cong 1 + C_1(1 - \alpha)$$

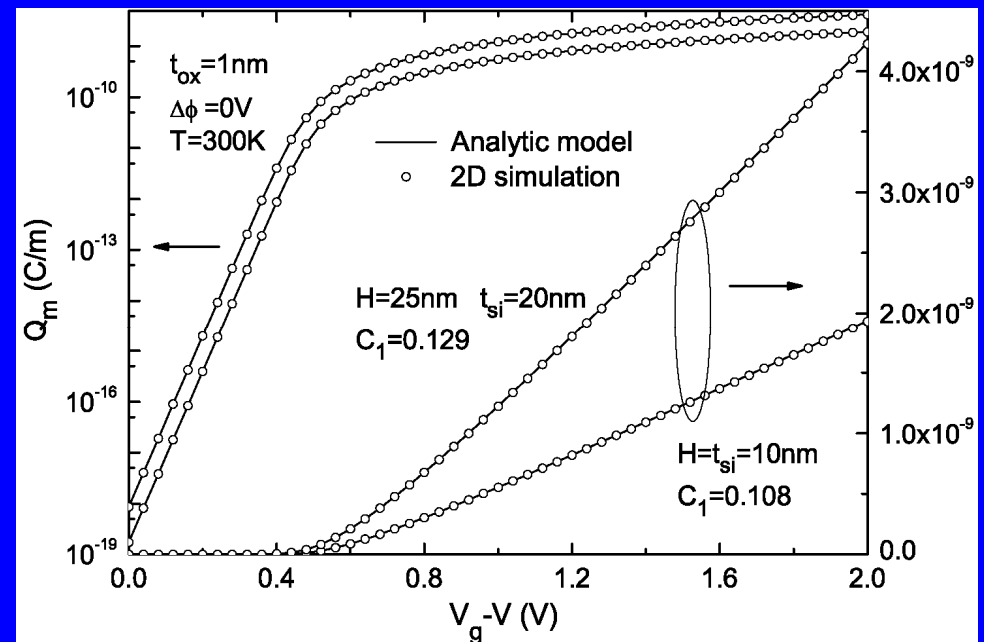
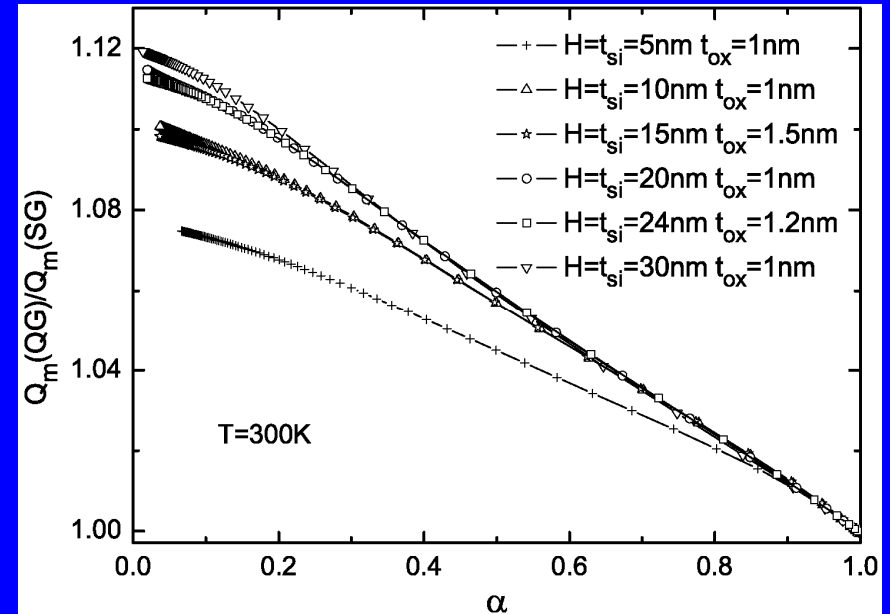
$\alpha \approx 1$ ➔ **subthreshold**

$\alpha \ll 1$ ➔ **above threshold**

➤ C_1 is a function of t_{si}/t_{ox} and H/t_{ox} , determined by 2D simulation.

- Analytic model for QG MOS:

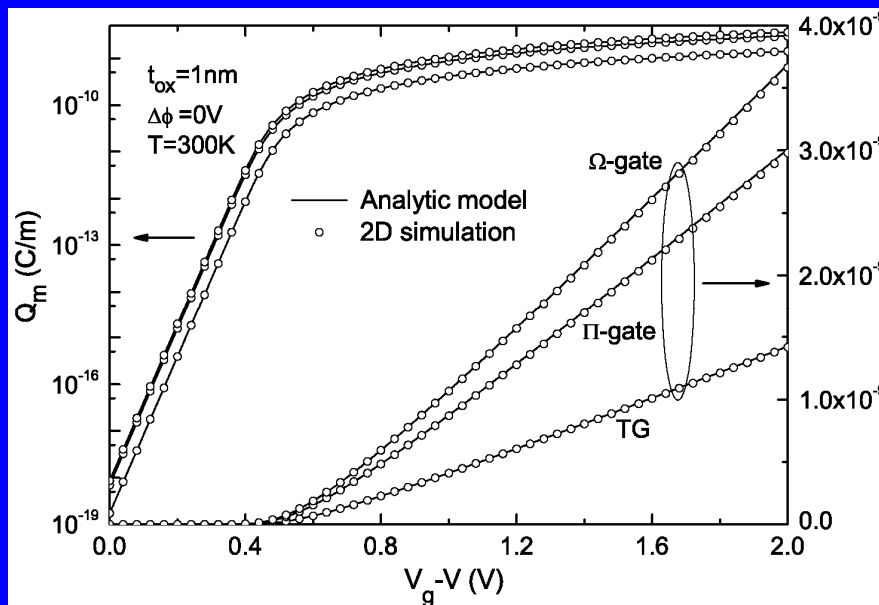
$$Q_m(QG) = 8\pi\epsilon_{si} \frac{kT}{q} \frac{1 - \alpha}{\alpha} \times [1 + C_1(1 - \alpha)]$$



Analytic Model for TG and TPG MOS Capacitor

- Approximated by $[(1+C_2)*QG+(1-C_2)*DG]/2$; C_2 determined by simulation

$$Q_m = (1 + C_2) 4\pi\epsilon_{si} \frac{kT}{q} \frac{1 - \alpha}{\alpha} [1 + C_1(1 - \alpha)] + (1 - C_2) 4\epsilon_{si} \frac{H}{t_{si}} \frac{kT}{q} \beta \tan \beta$$



π -gate: $C_2=0.218$
 Ω -gate: $C_2=0.440$

Device	H	t_{si}	t_{ox}	C_1	C_2
DG	W	t_{si}	t_{ox}	0	-1
SG	$\sqrt{\pi}R$	$\sqrt{\pi}R$	t_{ox}	0	1
QG	H	t_{si}	t_{ox}	C_1	1
TG	H	t_{si}	t_{ox}	C_1	0
TPG	H	t_{si}	t_{ox}	C_1	C_2

Unified Analytic Drain Current Model

- Based on MOS capacitor behaviors, one can carry out Pao-Sah integral to obtain current

$$I_{ds} = \frac{\mu}{L} \int_{V_s}^{V_d} Q_m(V_g, V) dV$$

$$I_{ds} = \mu \frac{4\pi\epsilon_{si}}{L} \left(\frac{kT}{q}\right)^2 (1+C_2) [f(\alpha) + C_1 d(\alpha)] \Big|_{\alpha_s}^{\alpha_d}$$

$$+ \mu \frac{4\epsilon_{si}}{L} \frac{H}{t_{si}} \left(\frac{kT}{q}\right)^2 (1-C_2) [p(\beta)] \Big|_{\beta_s}^{\beta_d}$$

$$f(\alpha) = \left(-2/\alpha - \ln \alpha\right) + s \left(-1/\alpha^2 + 2/\alpha\right)$$

$$p(\beta) = -2\beta \tan \beta + \beta^2 - 2r\beta^2 \tan^2 \beta$$

α and β at source/drain are calculated from the boundary conditions

$$d(\alpha) = \left(-\frac{2}{\alpha} - 3\ln \alpha + \alpha\right)$$

$$+ s \left(-\frac{1}{\alpha^2} + \frac{4}{\alpha} + 2\ln \alpha\right)$$

A core long-channel compact model for DG, SG, QG, TG, and TPG MOSFETs

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- INTRODUCTION
- SYMMETRIC MG MOSFETS: PLANAR AND CYLINDRICAL
- A COMPLETE DOUBLE-GATE COMPACT MODEL WITH HARDWARE CALIBRATION
- GENERALIZATION OF CORE MODEL TO MULTIPLE-GATE MOSFETS
- **OTHER APPROACHES**
- CONCLUSION

BSIM-CMG

- BSIM-CMG includes doping effect with a perturbation term to the undoped Poisson's Eq. :

$$\frac{d^2\psi}{dx^2} = \frac{qn_i}{\epsilon_{Si}} \left(e^{\frac{q\psi}{kT}} e^{\frac{-q\phi_B}{kT}} e^{\frac{-qV_{ch}}{kT}} + e^{\frac{q\phi_B}{kT}} \right)$$

- Three coupled implicit equations need to be solved

$$\psi_{inv} = \psi_1 \Big|_{x=-\frac{T_{Si}}{2}} = \psi_0 - \frac{2kT}{q} \ln \left(\cos \left(\sqrt{\sqrt{\frac{q^2 n_i^2}{2\epsilon_{Si} kT} N_A} e^{\frac{-qV_{ch}}{kT}} e^{\frac{qV_0}{2kT}} \frac{T_{Si}}{2}}} \right) \right)$$

$$\psi_C = \frac{2qn_i}{\epsilon_{Si}} \frac{e^{\frac{q\phi_B}{kT}}}{a} \left(\frac{e^{\frac{T_{Si}\sqrt{a}}{2}} - 1}{2e^{\frac{T_{Si}\sqrt{a}}{2}}} \right)^2 \quad \text{where} \quad a = \frac{q^2 n_i}{\epsilon_{Si} kT} e^{\frac{q(\psi_{inv} - V_{ch} - \phi_B)}{kT}}$$

$$V_g = V_{FB} + \psi_s + \frac{\epsilon_{Si}}{C_{ox}} \sqrt{\frac{2qn_i}{\epsilon_{Si}} \left(\frac{e^{\frac{q\psi_s}{kT}} - e^{\frac{q\psi_0}{kT}}}{q/kT} e^{\frac{-q\phi_B}{kT}} e^{\frac{-qV_{ch}}{kT}} + e^{\frac{q\psi_B}{kT}} (\psi_s - \psi_0) \right)}$$

Charge-Sheet Current Expression

- Charge Sheet Current used in BSIM-CMG and others

$$I_{ds,CSA} = -\mu W \left(Q \frac{d\psi_s}{dy} - \frac{kT}{q} \frac{dQ}{dy} \right)$$

- Not generally consistent with the rigorous integration of drift-diffusion current density because $d\psi/dy$ is a function of x .

$$I_{ds} = -\mu W \int_{t_{si}/2}^{-t_{si}/2} qn \left(\frac{d\psi}{dy} - \frac{kT}{qn} \frac{dn}{dy} \right) dx = -\mu W \left(\int_{t_{si}/2}^{-t_{si}/2} qn \frac{d\psi}{dy} dx - \frac{kT}{q} \frac{dQ}{dy} \right)$$

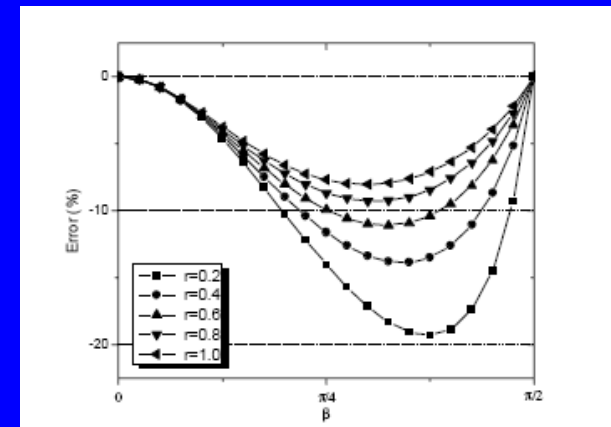
- From the Analytic Potential Model

- Current Expressions in terms of β

$$I_{ds,CSA} = \mu \frac{W}{L} \frac{8\epsilon_{si}}{t_{si}} \left(\frac{kT}{q} \right)^2 \left| -\beta \tan \beta - 2r\beta^2 \tan^2 \beta \right|_{\beta_s}^{\beta_d}$$

$$I_{ds} = \mu \frac{W}{L} \frac{8\epsilon_{si}}{t_{si}} \left(\frac{kT}{q} \right)^2 \left| -2\beta \tan \beta + \beta^2 - 2r\beta^2 \tan^2 \beta \right|_{\beta_s}^{\beta_d}$$

- As much as ~20% error in the transition region.



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Compact Modeling of Multiple-Gate MOSFETs

- For highly symmetric planar DG and cylindrical SG MOSFETs, Poisson's and current continuity eqs. have been solved analytically to derive continuous I–V models for all regions without the charge-sheet approximation. Accurate explicit solutions have been developed for both DG and SG MOSFETs.
- The DG core model has been expanded into a complete compact model with short-channel and quantum effects, charge and capacitance models. The full DG model has been calibrated with FinFET hardware data.
- Based on the asymptotic behavior of inversion charge density and with combinations of the core DG and SG models, a unified approach has been presented to develop core models for the less symmetric quadruple-gate, triple-gate, Π -gate, and Ω -gate MOSFETs.